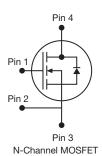
Vishay Siliconix

HALOGEN FREE

# **E Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	550			
R <sub>DS(on)</sub> max. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.147		
Q <sub>g</sub> max. (nC)	70			
Q <sub>gs</sub> (nC)	9			
Q <sub>gd</sub> (nC)	15			
Configuration	Single			





#### **FEATURES**

- Completely lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH20N50E-T1-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	500	V	
Gate-Source Voltage			$V_{GS}$	± 30	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	22	А	
	V <sub>GS</sub> at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		14		
Pulsed Drain Current a			I <sub>DM</sub>	53		
Linear Derating Factor				1.4	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	286	mJ	
Maximum Power Dissipation			$P_{D}$	174	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Drain-Source Voltage Slope	$T_{J} = 12$	T <sub>J</sub> = 125 °C		70	- V/ns	
Reverse Diode dV/dt <sup>c</sup>	•		dV/dt	19		

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD} = 140 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 28.2 \, \text{mH}$ ,  $R_q = 25 \, \Omega$ ,  $I_{AS} = 4.5 \, \text{A}$ .
- c.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .



Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R <sub>thJA</sub>	40	52	°C/W		
Maximum Junction-to-Case (Drain)	$R_{thJC}$	0.55	0.72	G/ <b>V</b> V		

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		500	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.56	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		-	4.0	V
Cata Saurea Laglaga		V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-Source Leakage	I <sub>GSS</sub>	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zara Cata Valtaga Drain Current	1		V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V		-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 400 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	25	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A	-	0.128	0.147	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 10 A		-	8.4	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1  MHz		-	2063	-	pF
Output Capacitance	C <sub>oss</sub>			-	108	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	7	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		-	91	-	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	282	-	
Total Gate Charge	Qg			-	56	84	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 10 \text{ A}, V_{DS} = 400 \text{ V}$		12	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	7		-	23	-	1 '
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 10 A,		-	22	44	- ns
Rise Time	t <sub>r</sub>			-	41	82	
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		67	101	
Fall Time	t <sub>f</sub>	1		-	41	82	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz		0.3	0.6	1.2	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	22	^
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	53	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 10 A, V <sub>GS</sub> = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 10 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	271	542	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	3.5	7.0	μC
Reverse Recovery Current	I <sub>RRM</sub>			_	24	-	A

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .

b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

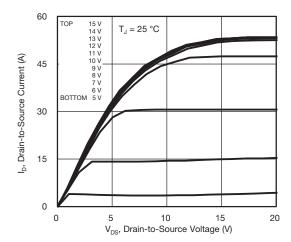


Fig. 1 - Typical Output Characteristics

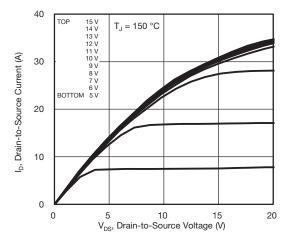


Fig. 2 - Typical Output Characteristics

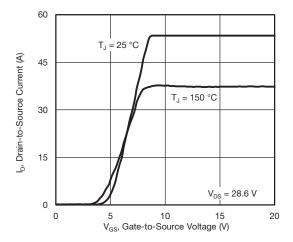


Fig. 3 - Typical Transfer Characteristics

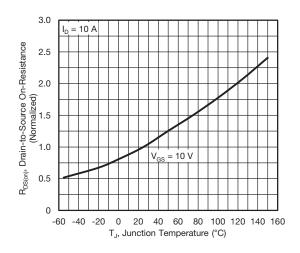


Fig. 4 - Normalized On-Resistance vs. Temperature

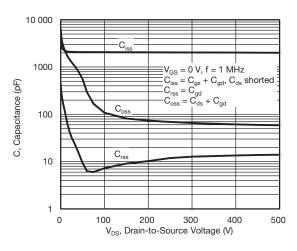


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

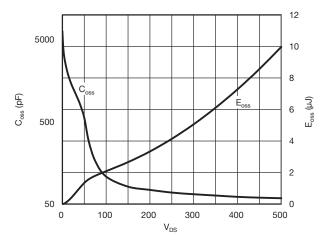


Fig. 6 -  $C_{OSS}$  and  $E_{OSS}$  vs.  $V_{DS}$ 



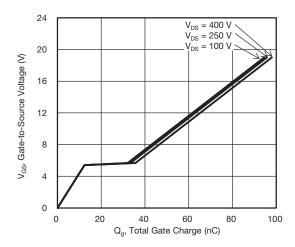


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

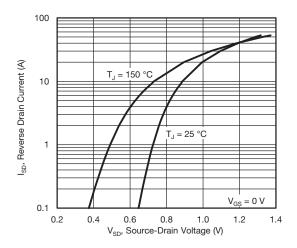


Fig. 8 - Typical Source-Drain Diode Forward Voltage

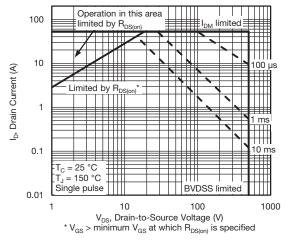


Fig. 9 - Maximum Safe Operating Area

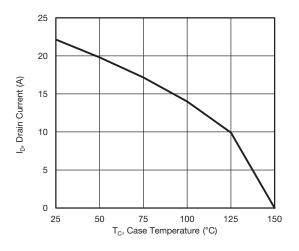


Fig. 10 - Maximum Drain Current vs. Case Temperature

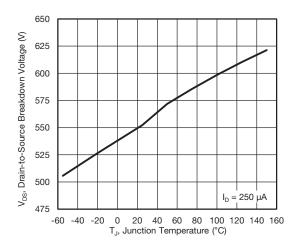


Fig. 11 - Temperature vs. Drain-to-Source Voltage



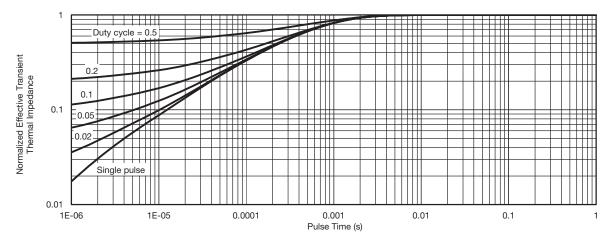


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

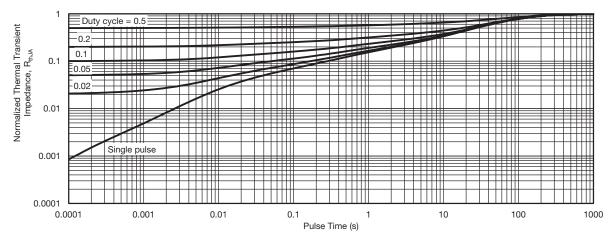


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

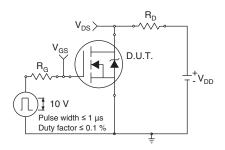


Fig. 14 - Switching Time Test Circuit

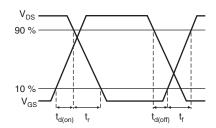


Fig. 15 - Switching Time Waveforms

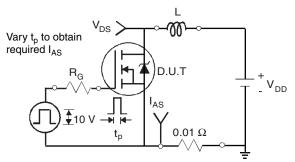


Fig. 16 - Unclamped Inductive Test Circuit

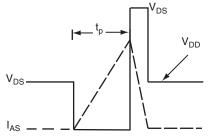
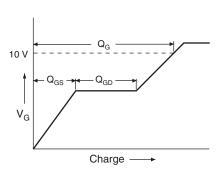


Fig. 17 - Unclamped Inductive Waveforms







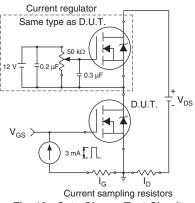
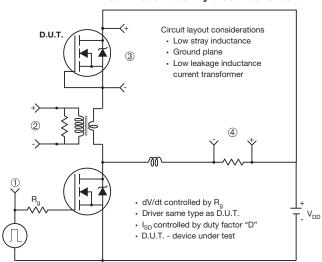


Fig. 19 - Gate Charge Test Circuit

#### Peak Diode Recovery dV/dt Test Circuit



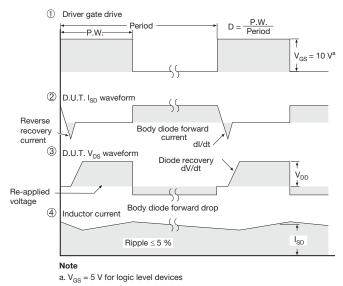


Fig. 20 - For N-Channel

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